

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6314846

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
NISHANT AGRAWAL	09/21/2020
PANKESH BAMOTRA	09/21/2020
EMILY HUA	09/21/2020
ASHUTOSH PENDSE	09/21/2020
SUNGHO KIM	09/21/2020
CHAN SEO	09/21/2020
MIN HYUN PARK	09/22/2020
RECEIVING PARTY DATA	
Name:	COUPANG CORP.
Street Address:	570 SONGPA-DAERO, SONGPA-GU
City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
Postal Code:	05510
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17030282
CORRESPONDENCE DATA	
Fax Number:	(202)408-4400
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	202-408-4000
Email:	regional-desk@finnegan.com
Correspondent Name:	FINNEGAN, HENDERSON, FARABOW, GARRETT &
Address Line 1:	901 NEW YORK AVENUE, NW
Address Line 4:	WASHINGTON, D.C. 20001-4413
ATTORNEY DOCKET NUMBER:	14904.0202-00000
NAME OF SUBMITTER:	CHARLENE WOODS
SIGNATURE:	/Charlene Woods/
DATE SIGNED:	09/23/2020

Total Attachments: 4

source=14904-0202 (IDF No. 230) Declaration and Assignment#page1.tif

source=14904-0202 (IDF No. 230) Declaration and Assignment#page2.tif

source=14904-0202 (IDF No. 230) Declaration and Assignment#page3.tif

source=14904-0202 (IDF No. 230) Declaration and Assignment#page4.tif

ASSIGNMENT AND DECLARATION FOR UTILITY OR DESIGN PATENT APPLICATION

I am an inventor (referred to below as Assignor) of an invention entitled:

**SYSTEMS AND METHODS FOR PROVIDING INTELLIGENT MULTI-DIMENSIONAL RECOMMENDATIONS DURING
ONLINE SHOPPING**

filed herewith. Coupang Corp., a corporation of Republic of Korea whose address is 570 Songpa-daero, Songpa-gu, Seoul, 05510 Republic of Korea (hereinafter referred to as Assignee), desires to obtain an assignment of this invention;

THEREFORE, for good and valuable consideration, I have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over to Assignee, its successors and assigns, my entire right, title, and interest in and to this invention, and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues and reexaminations thereof, as well as all rights to claim priority on the basis of this application in any foreign country, and all applications for Letters Patent which may become filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, reexaminations and reissues thereof; and I authorize and request the Director of the United States Patent and Trademark Office (USPTO) and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I covenant that I have the full right to convey the interest assigned by this Assignment, and I have not executed and will not execute any agreement in conflict with this Assignment;

AND, I further covenant and agree that I will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, I authorize and request that the attorneys having Power of Attorney in this application, insert here in parentheses (Application No. _____, filed _____) the filing date and application number of said application when known.

DECLARATION:

As a named inventor below, I declare that: (1) This declaration is directed to the above-identified application; (2) the above-identified application was made or authorized to be made by me; (3) my mailing address is as stated below next to my name; and (4) I believe I am an original inventor or an original joint inventor of a claimed invention in the application. I acknowledge that any willful false statements made in this declaration are punishable by fine or imprisonment of not more than five (5) years, or both, under section 1001 of Title 18 of the United States Code.

As a below named inventor, I have reviewed and understand the contents of the application, including the claims, and am aware of the duty to disclose to the USPTO all information known to me to be material to patentability as defined in 37 C.F.R. § 1.56.

Assignor (Inventor) 1:

Name: Nishant AGRAWALAddress: 570 Songpa-daero, Songpa-gu, Seoul, 05510 Republic of KoreaSignature: / Nishant Agrawal /Date: 9/21/2020

Assignor (Inventor) 2:

Name: Pankesh BAMOTRAAddress: 570 Songpa-daero, Songpa-gu, Seoul, 05510 Republic of KoreaSignature: / Pankesh Bamotra /Date: 9/21/2020

Assignor (Inventor) 3:

Name: Emily HUAAddress: 570 Songpa-daero, Songpa-gu, Seoul, 05510 Republic of KoreaSignature: / Emily Hua /Date: 9/21/2020

Assignor (Inventor) 4:

Name: Ashutosh PENDSEAddress: 570 Songpa-daero, Songpa-gu, Seoul, 05510 Republic of KoreaSignature: / Ashutosh Pendse /Date: 9/21/2020

Assignor (Inventor) 5:

Name: Sungho KIMAddress: 570 Songpa-daero, Songpa-gu, Seoul, 05510 Republic of KoreaSignature: / 김성호 /Date: 9/21/2020

Assignor (Inventor) 6:

Name: Chan SEOAddress: 570 Songpa-daero, Songpa-gu, Seoul, 05510 Republic of KoreaSignature: / Seo Chan /Date: 9/21/2020

Assignor (Inventor) 7:

Name: Min Hyun PARK

Address: 570 Songpa-daero, Songpa-gu, Seoul, 05510 Republic of Korea

Signature: / Min Hyun Park /

Date: 9/22/2020